Precise flattening and correction of features on a wafer

Key Benefits

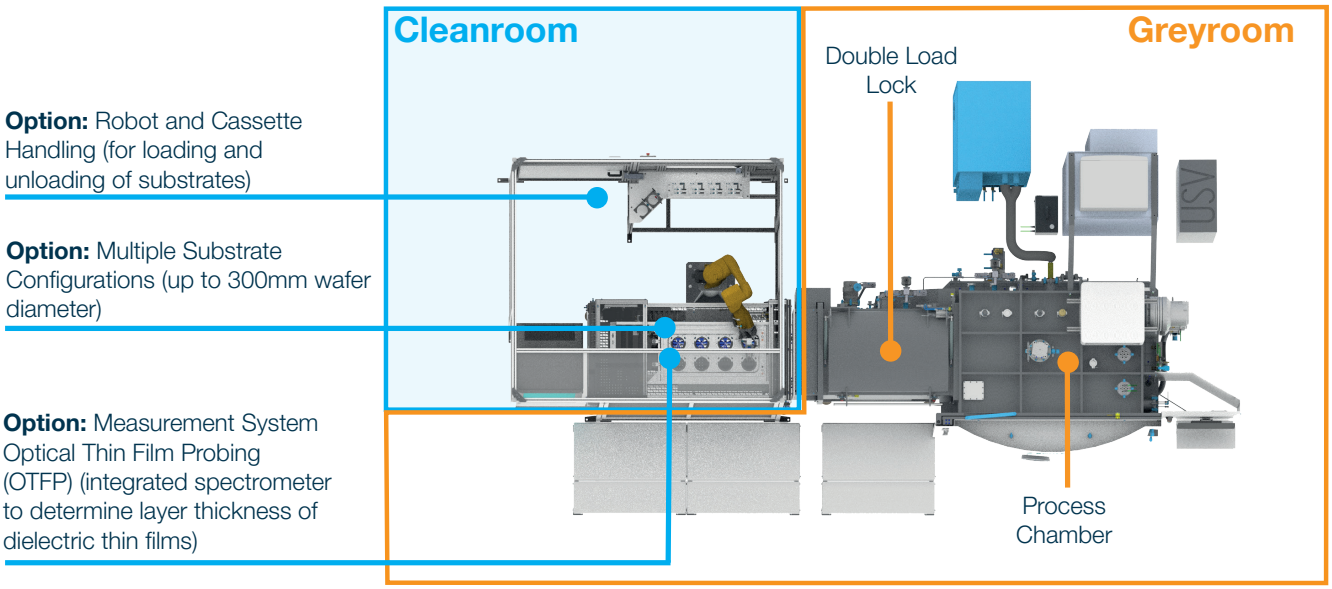
- High productivity due to automated handling, batch processing and double load lock;
- Integrated metrology;
- Process variety and adaptability for a wide range of applications (different ion beam diameters to choose within process);
- Well-proven ion beam technology;
- Customer service worldwide;

Application Examples

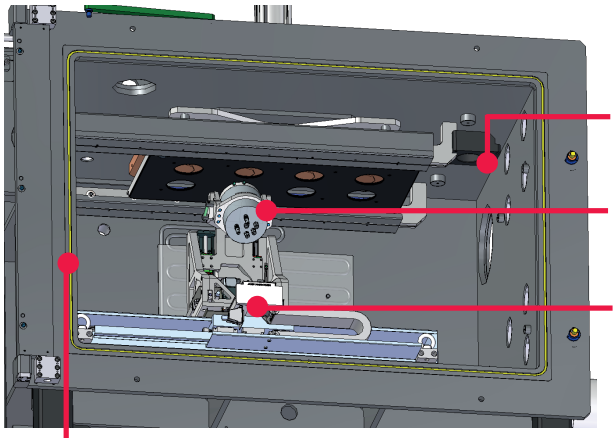
- Radio frequency communication (RF connectivity)
- High performance sensor & actuator market (SAW, BAW, etc.)
- Micro-electro-mechanical systems (MEMS)
- Wafer-level bonding
- Silicon on insulator (SOI)
- Manufacturers of micro and nano electronics
- High-end optics

Solution

Tailored solution based on our flexible machine, configured out of modules for process, handling, metrology and software, which are built in semiconductor fabrication environment for machining substrates up to Ø300mm.



Process Chamber



Additional Options:
Additional turbomolecular pump, UPS system, Thermal imaging system for substrate and chamber, Cryogenerator System

Basic footprint: W3980 x D1770 x H1900 (doors closed)

Equipment Weight: 4700kg

Processible Material: LiN, LiTa, SiO2, Si and others

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